

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1.-17. (Cancelled)

Claim 18. (Previously Presented) An electronic device contained in a case member which is disposed in an air cleaner or an air duct of an automobile, comprising:

a substrate having electronic elements mounted thereon, and conductor wire films made of silver or silver alloys, the conductor wire films being connected to the elements;

an insulating overcoat film made of a material selected from the group consisting of glass and resin covering the surface of the device, including the conductor wire films; wherein,

the overcoat has openings through which surfaces of the conductor wire films are exposed;

the openings are formed in a shape having no square corners and no acute angle corners;

the entire exposed surfaces of the conductor wire films are covered with a solder whose main component is tin, whereby the exposed surfaces of the conductor wire films are protected from any corrosive gas that may enter the case member; and

said electronic elements and said insulating overcoat comprise thick film elements formed on said substrate.

Claim 19. (Previously Presented) An electronic device disposed in a case member placed in an air duct, comprising:

a substrate having conductor wire films made of silver or silver alloys and electronic elements mounted thereon, said electronic elements including at least one element selected from the group consisting of resistors, capacitors, inductors, and diodes, the conductor wire films being connected to the at least one element; and

an insulating overcoat film made of a material selected from the group consisting of glass and resin covering the surface of the device, including the conductor wire films; wherein

the overcoat has openings through which surfaces of the conductor wire films are exposed;

the openings are formed in a shape having no square corners and no acute angle corners;

the entire exposed surfaces of the conductor wire films are covered with a solder whose main component is tin, whereby the exposed surface of the conductor wire films are protected from any corrosive gas that may enter the case member; and

said electronic elements and said insulating overcoat comprise thick film elements formed on said substrate.

Claim 20. (Previously Presented) The electronic device according to Claim 18, wherein the openings have a shape that is selected from the group consisting of a round, elliptical, rectangular with round corners, and rectangular with chamfered corners.

Claim 21. (Previously Presented) The electronic device according to Claim 18, wherein the openings are covered with a conductive metal paste.

Claim 22. (Previously Presented) The electronic device according to Claim 18, wherein the substrate has at least two layers.

Claim 23. (Cancelled)

Claim 24. (Previously Presented) An electronic device for a case member disposed in an air duct of an automobile, comprising:

a substrate having conductor wire films made of silver or a silver alloy mounted thereon; and

an insulating overcoat film made of an insulating material covering the conductor wire films; wherein

the overcoat has an opening having no acute angle corner wherein a surface of the conductor wire films is exposed through an opening formed in the overcoat; and

the surface of the exposed conductor wire film is covered with a solder whose main component is tin.

Claim 25. (Currently Amended) An electronic device for a case member disposed in an air duct of an automobile, comprising:

a substrate having a resistor film mounted thereon, the resistor having conductor wire films and terminals connected thereto; and

an overcoat film made of an insulator covering the resistor, the conductor wire films, and the terminals; wherein,

the overcoat film has an opening formed in a shape having no acute angle corners wherein a surface of the conductor wire films is exposed; and

the exposed surface of the conductor wire films is covered with a solder whose main component is tin.